



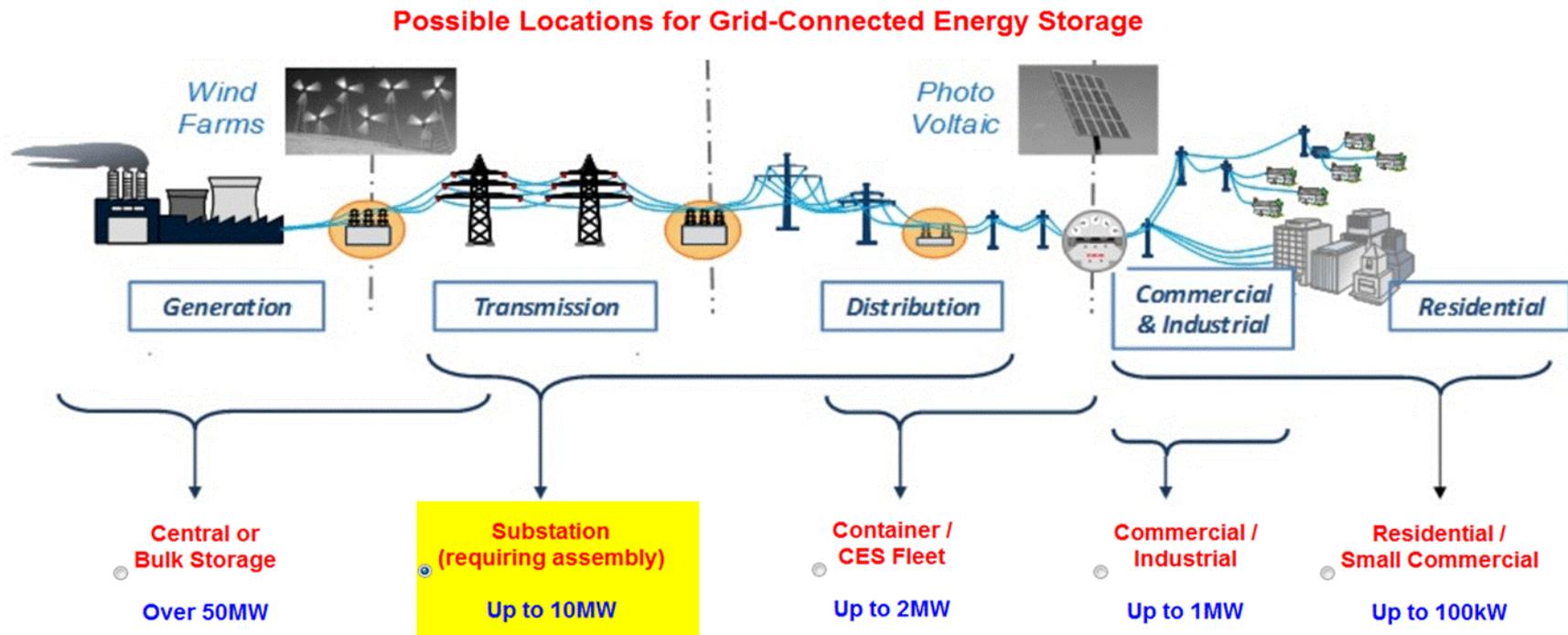
Efficient power electronics enabled by 3.3kV Silicon Carbide Switches

GeneSiC Semiconductor Inc.
NC State University (S. Bhattacharya)
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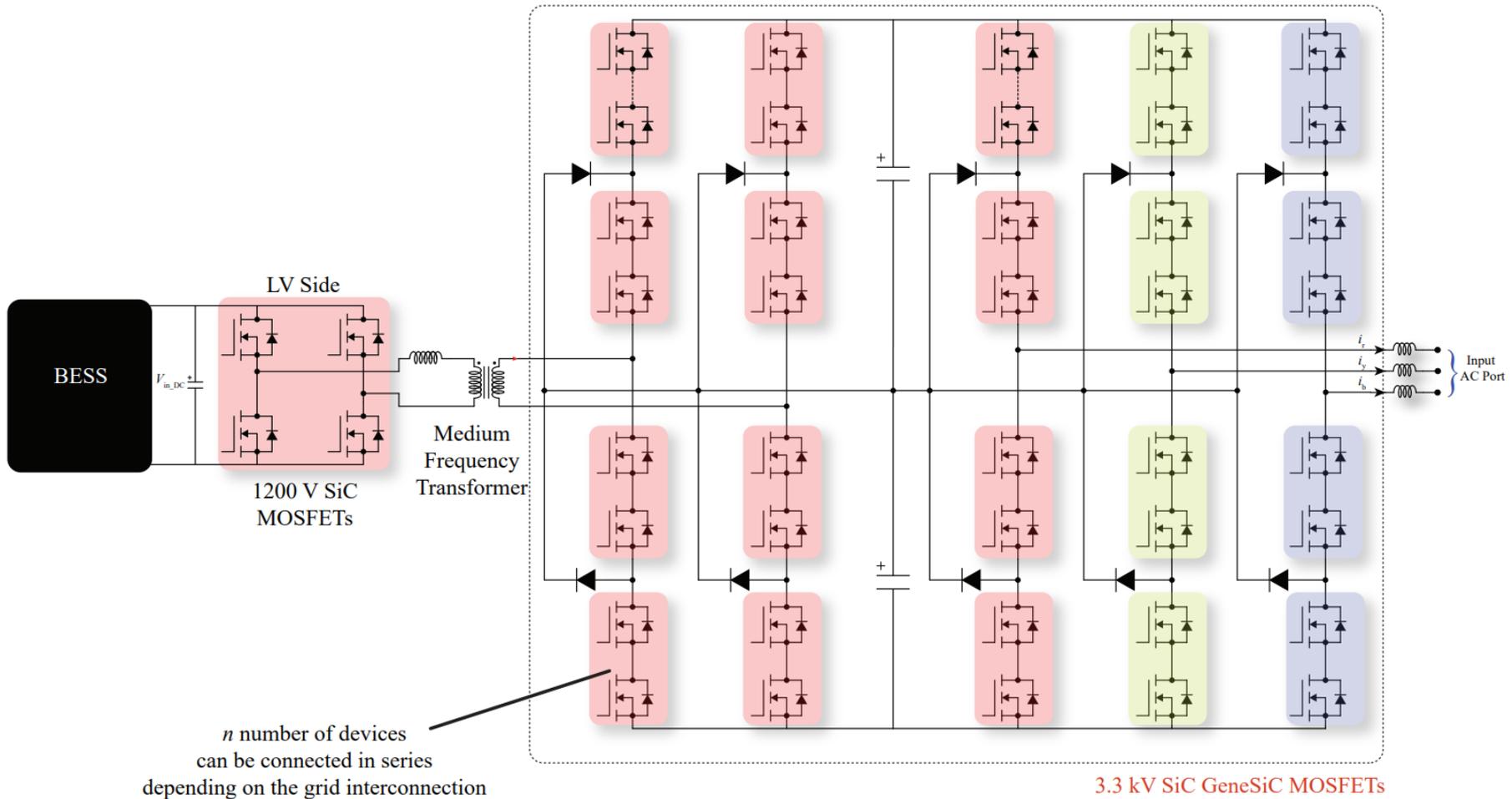
GeneSiC
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Energy Storage Opportunities at Medium Voltages (3-20 kV)



- Many Energy storage opportunities require power electronics that can enable conversion efficiencies needed for making energy storage viable
- Silicon Carbide high voltage devices will play a pivotal role

Direct Grid Connection of BESS



Calculated Loss Comparisons at 1 MVA

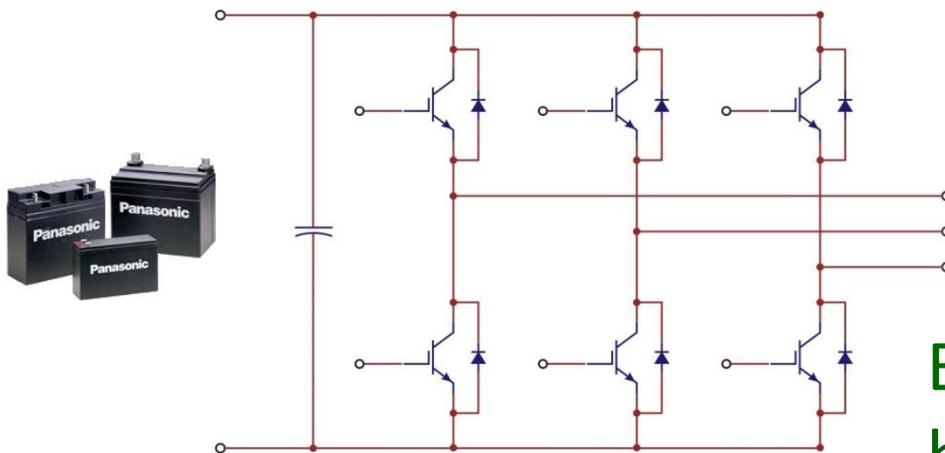
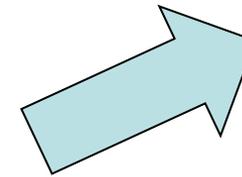
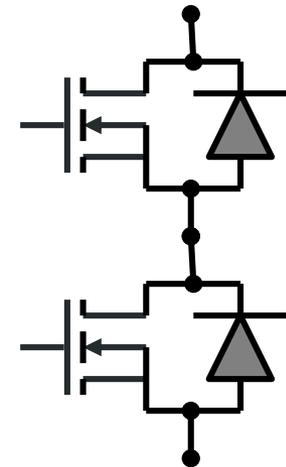
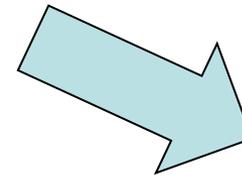
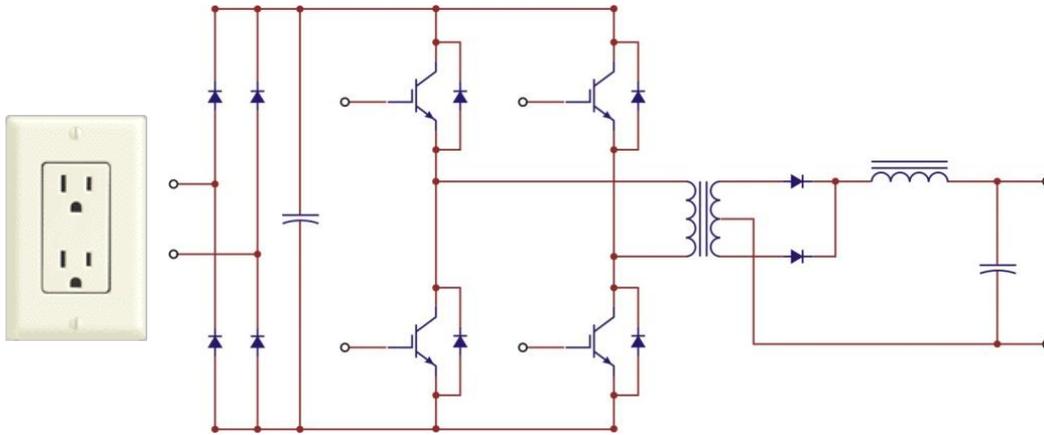
Table 1: Medium Voltage/Low Current Side loss even at 1 MVA operation.

Active Power (MW)	Reactive Power (MVAR)	Loss (W)
1	0	3064
0.8	0.6	4175
0.6	0.8	5330

Table 2: Low Voltage/ High Current Side Loss

Active Power (MW)	Reactive Power (MVAR)	Loss (kW)
1	0	32
0.8	0.6	27
0.6	0.8	23

Phase Leg forms fundamental building block for AC/DC AND DC/AC Conversion



Each switch and diode must be capable of bus voltage

Awards and Recognitions

SiC-Based Monolithic Transistor-Rectifier
Semiconductor Switch

R&D 100 Gold Award Winner

R&D 100
CONFERENCE & AWARDS
San Francisco, CA

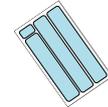


2016 → GeneSiC named among Top-30 Power Semiconductor Companies by EETimes

2016 → EETimes recognized GeneSiC's Founder as "Forty of the Top Innovators Changing the Face of Electronics"

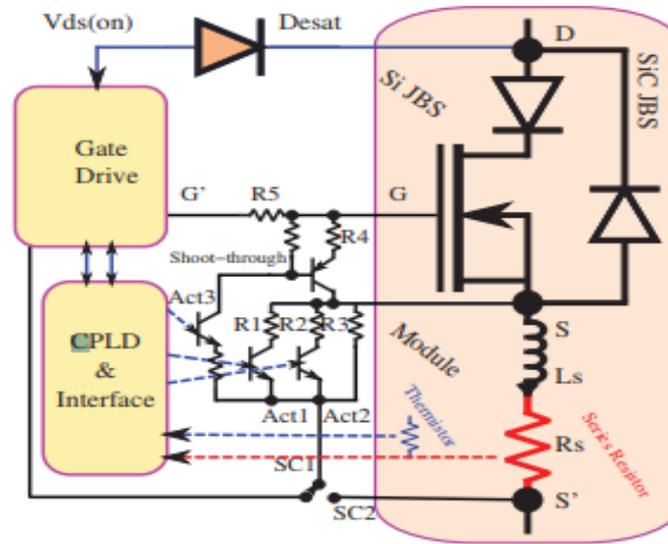
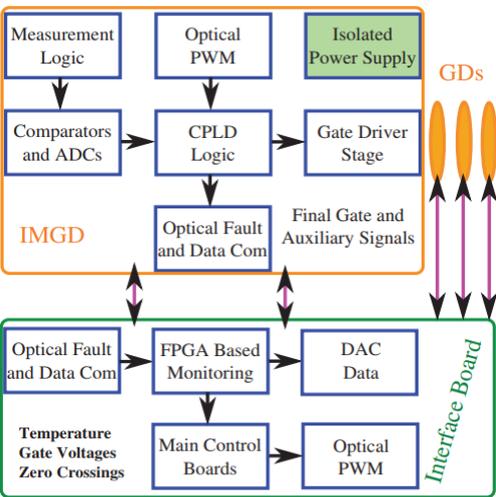
2019 → R&D100 Award : SiC-based Monolithic Transistor-Rectifier Semiconductor Switch

3300V – SiC MOSFETs



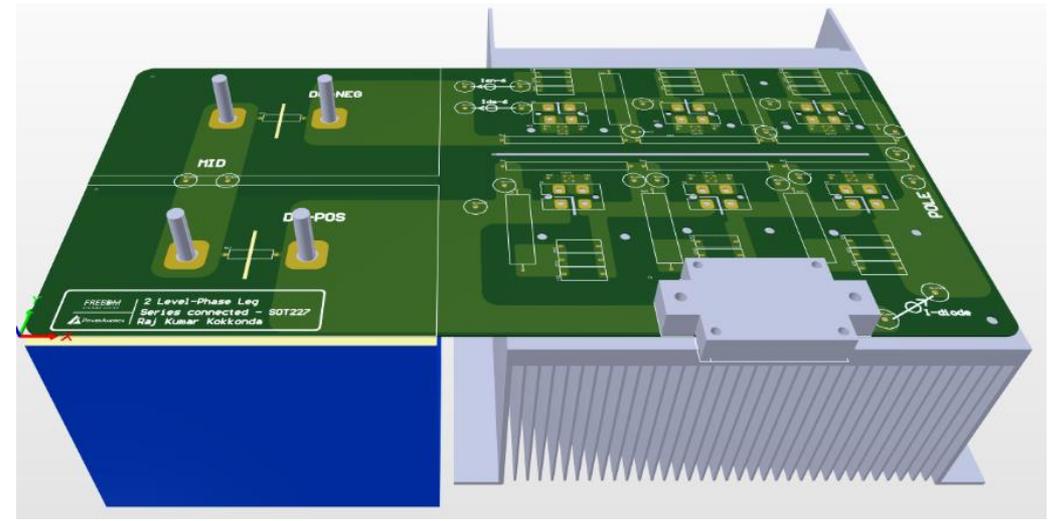
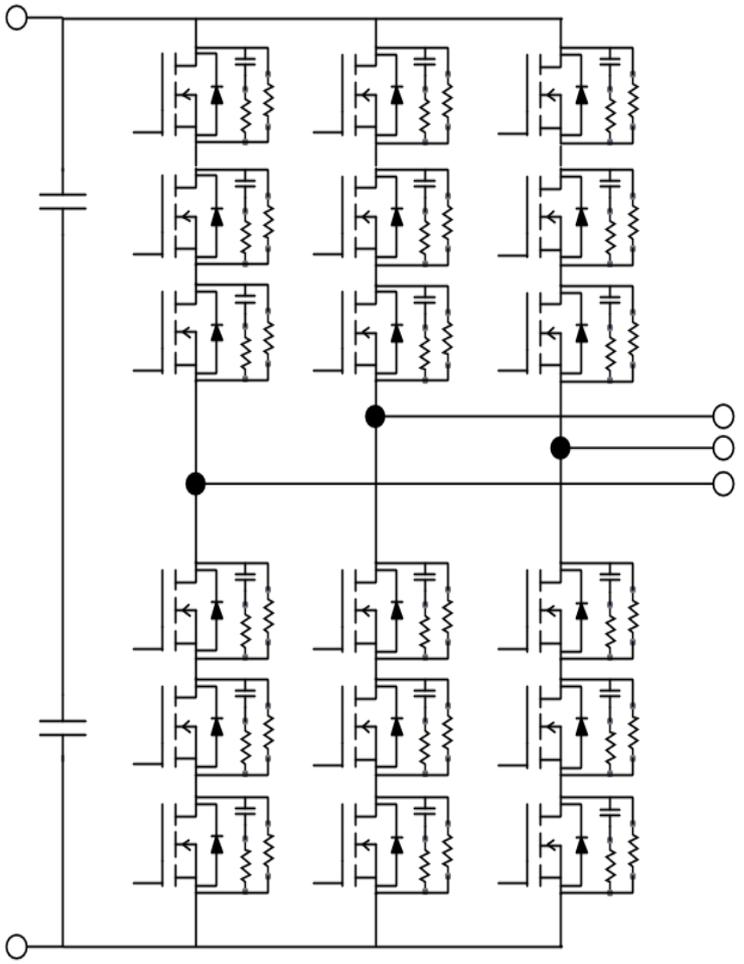
		TO-263-7 (D2PAK-7L)	SOT-227	Bare Chip
SiC MOSFETs (MT Series)	50 mΩ			G3R50 <u>MT</u> 33-CAL
	100 mΩ	G3R100 <u>MT</u> 33J		G3R100 <u>MT</u> 33-CAL
	450 mΩ	G3R100 <u>MT</u> 33J		
	1000 mΩ	G2R1000 <u>MT</u> 33J		
SiC Integrated-Schottky MOSFETs (MS Series)	60 mΩ <i>(Engineering Sample)</i>		G3R60 <u>MS</u> 33N	
	100 mΩ <i>(Engineering Sample)</i>	G3R80MS33J		

Active Gating and Protection Circuits



Block Diagram of Intelligent MV Gate Driver; Active gating and protection circuits; Intelligent Gate Driver Circuit Board

Board Layout Completed





Conclusions

- GeneSiC-NC State Team will demonstrate:
- 3.3kV/50 A MOSFET-diode Integrated Device
 - Intelligent Gate Driver with active sensing and control algorithms for stable performance
 - 400 MVA circuit demonstration and system in Phase II

Status and Future Efforts

- Current Status
 - Project Started in July 2019 (Phase II on Aug 2020)
 - 3.3kV Monolithically Integrated SiC MOSFET-Schottky Diodes commercialized
 - Gate Driver circuits completed at NCSU/FREEDM
 - Modeling of Circuit Losses being conducted
- Future Efforts
 - Complete SPICE Modeling of Devices to be used
 - Demonstrate 3.3kV MOSFET-Diodes in BESS
 - Quantify the impact of Monolithic 3.3kV MOSFET-Diode in power electronics on grid-tied energy storage systems



Grant Details

- Principal Investigator: Dr. Ranbir Singh and Prof. Subhashish Bhattacharya
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